

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

Claims 1-21 (Canceled)

Claim 22 (Currently amended): A method of making an electronics module, where said electronics module is to operate at one of a predetermined plurality of operating speeds, said method comprising:

providing a plurality of integrated circuits;

assembling an electronics module by demountably attaching selected ones of said integrated circuits to a module substrate;

testing said demountably assembled module at a selected one of said operating speeds;  
if said module fails said testing:

removing at least one of said integrated circuits determined to have caused said failure from said module substrate,

replacing said at least one removed integrated circuit with another of said plurality of integrated circuits, and

repeating said testing step and, if said module again fails said testing, said removing, replacing, and repeating steps,

further comprising grouping said plurality of integrated circuits in accordance with said operating speeds,

wherein:

said step of assembling an electronics module comprises selecting said integrated circuits from one of said groups; and

said selected one of said operating speeds corresponding to said one of said groups.

Claim 23 (Currently amended): The method of ~~claim 47~~ claim 22, wherein said step of grouping a plurality of integrated circuits in accordance with said operating speeds comprises:

determining an actual operating speed of each said integrated circuit; and  
grouping said integrated circuits in accordance with said actual operating speeds.

Claim 24 (Currently amended): The method of ~~claim 47~~ claim 22, wherein said step of grouping a plurality of integrated circuits in accordance with said operating speeds comprises:

determining an actual operating speed of each said integrated circuit;  
subtracting a guard band from said actual operating speed to obtain a guard-banded operating speed; and  
grouping said integrated circuits in accordance with said guard-banded operating speeds.

Claim 25 (Original): The method of claim 22, wherein:

each integrated circuit includes a plurality of input/output terminals and a plurality of conductive elongate interconnection elements attached to said input/output terminals, and  
said module substrate includes a plurality of contact locations for contacting said elongate interconnection elements.

Claim 26 (Original): The method of claim 25, wherein said step of assembling said module comprises:

bringing elongate interconnection elements attached to said selected integrated circuits into contact with corresponding ones of said contact locations, and  
demountably securing said selected integrated circuits to said module substrate.

Claim 27 (Original): The method of claim 26, wherein said step of demountably securing comprises applying a temporary force to said selected integrated circuits in a general direction of said module substrate.

Claim 28 (Original): The method of claim 27, wherein said step of removing said at least one integrated circuit comprises:

removing said temporary force from said at least one integrated circuit, and  
moving said at least one integrated circuit away from said module substrate.

Claim 29 (Original): The method of claim 26, wherein said step of demountably securing comprises clipping said selected integrated circuits to said module substrate.

Claim 30 (Original): The method of claim 29, wherein said step of removing said at least one integrated circuit comprises:

unclipping said at least one integrated circuit, and  
moving said at least one integrated circuit away from said module substrate.

Claim 31 (Original): The method of claim 26, wherein said step of demountably securing comprises wedging elongate interconnection elements attached to said selected integrated circuits in corresponding ones of said contact locations

Claim 32 (Original): The method of claim 31, wherein said step of removing said at least one integrated circuit comprises removing said elongate interconnection elements attached to said at least one integrated circuit from corresponding ones of said contact locations.

Claim 33 (Original): The method of claim 25, wherein said conductive elongate interconnection elements comprise spring contacts.

Claim 34 (Original): The method of claim 25, wherein said contact locations are selected from a group consisting of recesses, terminals, pads, holes, and vias.

Claim 35 (Original): The method of claim 22 further comprising:

if said module passes said testing, permanently securing to said module substrate said integrated circuits demountably secured to said module substrate.

Claim 36 (Original): The method of claim 35, wherein said step of permanently securing comprises soldering said elongate interconnection elements attached to said integrated circuits to corresponding ones of said contact locations.

Claim 37 (Original): The method of claim 35, wherein said step of permanently securing comprises applying an adhesive to adhere said integrated circuits to said module substrate.

Claim 38 (Original): The method of claim 22, wherein said assembling said electronics module comprises utilizing at least one die edge registration fixture formed on said module substrate to demountably attach said selected integrated circuits to said module substrate.

Claim 39 (Original): The method of claim 22, wherein said assembling said electronics module comprises utilizing a robotic work cell to demountably attach said elected integrated circuits to said module substrate.

Claim 40 (Currently amended): ~~The method of claim 22 further comprising:~~ A method of making an electronics module, where said electronics module is to operate at one of a predetermined plurality of operating speeds, said method comprising:

providing a plurality of integrated circuits;

assembling an electronics module by demountably attaching selected ones of said integrated circuits to a module substrate;

testing said demountably assembled module at a selected one of said operating speeds;

if said module fails said testing:

removing at least one of said integrated circuits determined to have caused said failure form said module substrate,

replacing said at least one removed integrated circuit with another of said plurality of integrated circuits , and  
repeating said testing step and, if said module again fails said testing, said removing, replacing, and repeating steps,

if said module passes said testing:

removing said integrated circuits from said module substrate, and

permanently securing said integrated circuits to a second module substrate.

Claims 41-51 (Canceled)

Claim 52 (Withdrawn): The method of claim 22, further comprising, if said module fails said testing, determining a number of said integrated circuits attached to said module substrate that caused said module to fail said testing.

Claim 53 (Withdrawn): The method of claim 52, wherein said steps of removing at least one of said integrated circuits, replacing said at least one removed integrated circuit, and repeating said testing are performed only if said module fails said testing and said number of integrated circuits attached to said module substrate that caused said module to fail said testing is less than a threshold number.

Claim 54 (Withdrawn): The method of claim 22 further comprising, if said module passes said testing, rating said module at said selected operating speed.

Claim 55 (Currently amended): ~~The method of claim 22;~~ A method of making an electronics module, where said electronics module is to operate at one of a predetermined plurality of operating speeds, said method comprising:

providing a plurality of integrated circuits;

assembling an electronics module by demountably attaching selected ones of said integrated circuits to a module substrate;

testing said demountably assembled module at a selected one of said operating speeds;

if said module fails said testing;

removing at least one of said integrated circuits determined to have caused said failure from said module substrate,

replacing said at least one removed integrated circuit with another of said plurality of integrated circuits , and  
repeating said testing step and, if said module again fails said testing, said removing, replacing, and repeating steps.

further comprising, if said module fails said testing, determining a number of times said module has failed said testing at said selected operating speed.

Claim 56 (Previously presented): The method of claim 55, wherein said steps of removing at least one of said integrated circuits, replacing said at least one removed integrated circuit, and repeating said testing are performed only if said module fails said testing and said number of times said module has failed said testing at said selected operating speed is less than a threshold number.

Claim 57 (Previously presented): The method of claim 56 further comprising repeating said testing step at a newly selected operating speed that is less than an operating speed selected during a previous execution of said testing step.